

/ Descriptions

Ultrafast Recovery Diode in a TO-220AC Plastic Package.

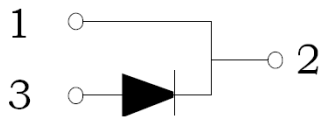
/ Features

Silicon epitaxial process to produce ultrafast recovery diode with low reverse leakage current and high reliability.

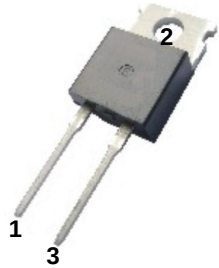
/ Applications

For high frequency, high voltage, high current rectifier diode, freewheeling diode.

/ Equivalent Circuit



/ Pinning



PIN1 2 Cathode

PIN 3 Anode

/ h_{FE} Classifications & Marking

See Marking Instructions

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	600	V
RMS Voltage	V_{RMS}	420	V
DC Blocking Voltage	V_{DC}	600	V
Average Forward Current	I_F	1 × 20	A
Peak forward surge current	I_{FSM}	250	A
Typical Thermal Resistance Junction to Case	R_{JC}	2.8	/W
Junction Temperature Range	T_J	150	
Storage Temperature Range	T_{stg}	-55 150	

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Forward Voltage	V_F	$I_F=5.0A \quad T_C=25$			1.35	V
		$I_F=5.0A \quad T_C=150$			1.15	
		$I_F=20A \quad T_C=25$			1.65	
		$I_F=20A \quad T_C=150$			1.25	
Instantaneous Reverse Current(Note1)	I_R	$V_R=600V \quad T_a=25$			0.25	mA
		$V_R=420V \quad T_a=150$			1.0	
		$V_R=600V \quad T_a=150$			2.0	
Reverse Recovery Time	t_{rr}	$I_F=0.5A \quad I_R=1.0A$ $I_{RR}=0.25A$			50	ns

Notes

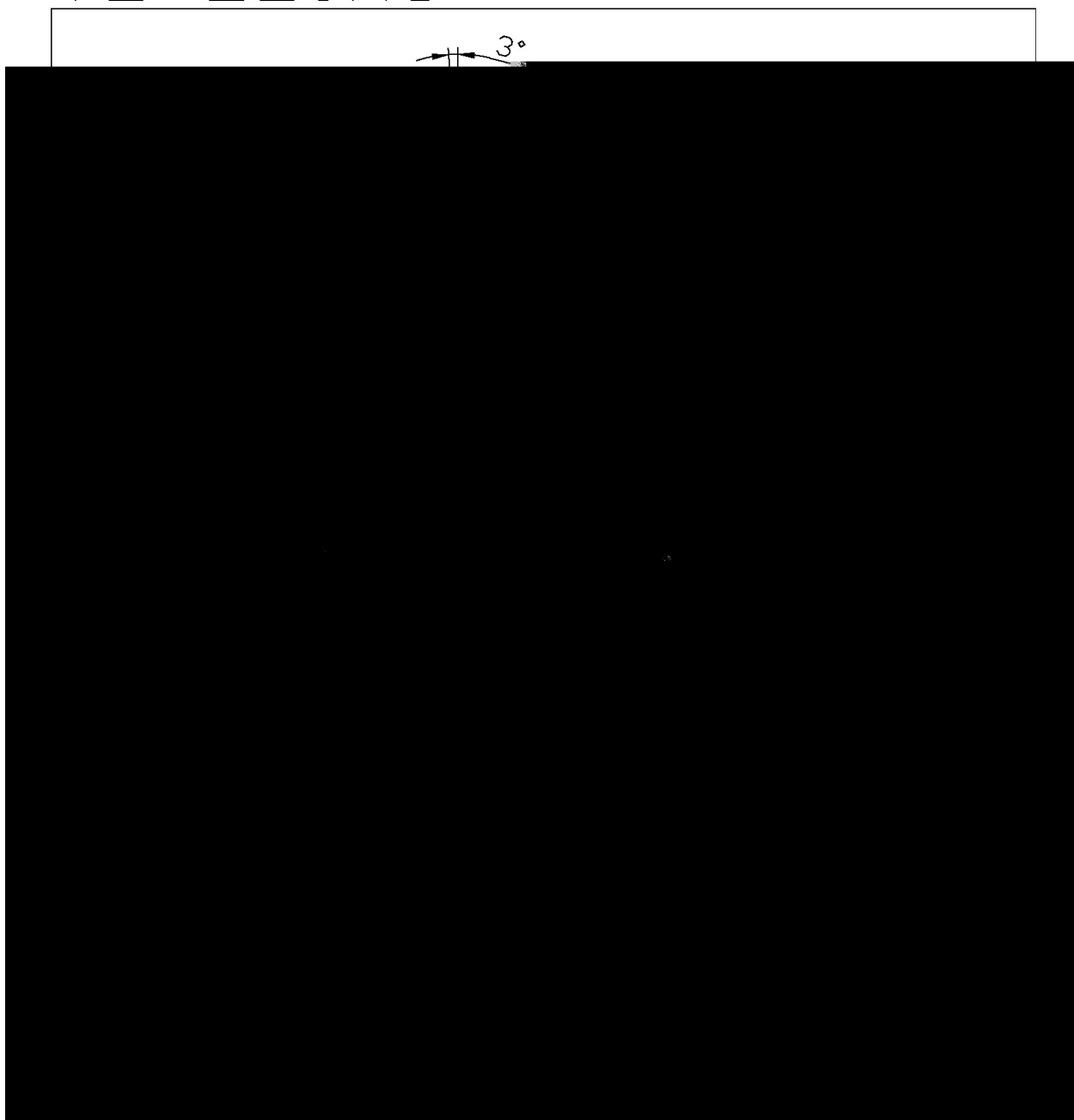
- Short duration pulse test used to minimize self-heating effect.
- Unless otherwise noted, values for the parameters of a single chip

MUR2060

/ Package Dimensions

TO-220AC

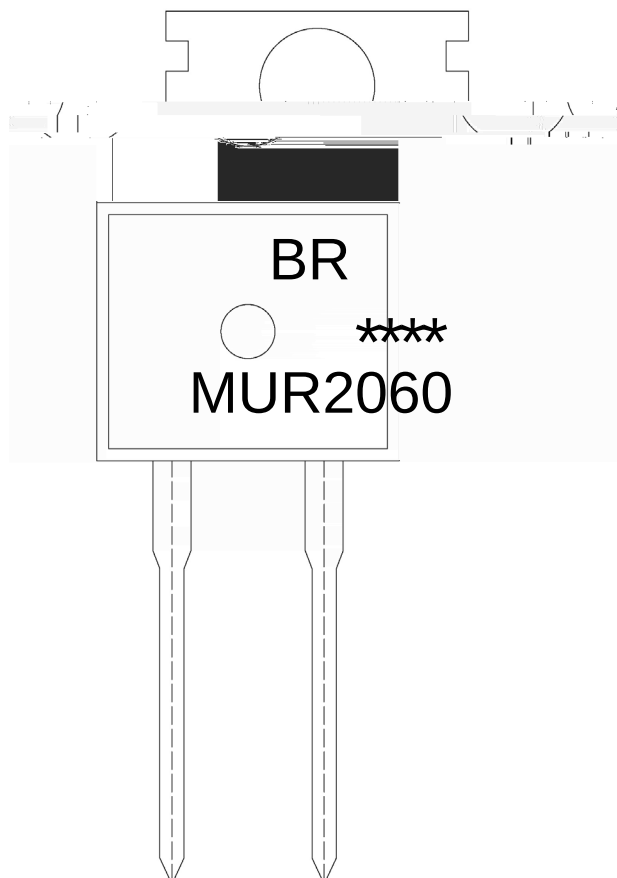
Unit:mm



The drawing shows a TO-220AC package with a 3° lead angle. Dimensions are provided in millimeters (mm).

Symbol	Min	Max	Symbol	Min	Max
A	9.0	12.0	D	6.0	6.7
R	3.56	3.64	B1	9.0	9.4
L	15.7	16.1	C1	2.2	2.6
b	12.6	13.6	C	1.2	1.4
b1	5.6	10.6	C	5.4	10.6
a	1.22	1.32	C2	4.3	4.7
a1	0.7	0.9			

/ Marking Instructions



Note:

BR:

Company Code

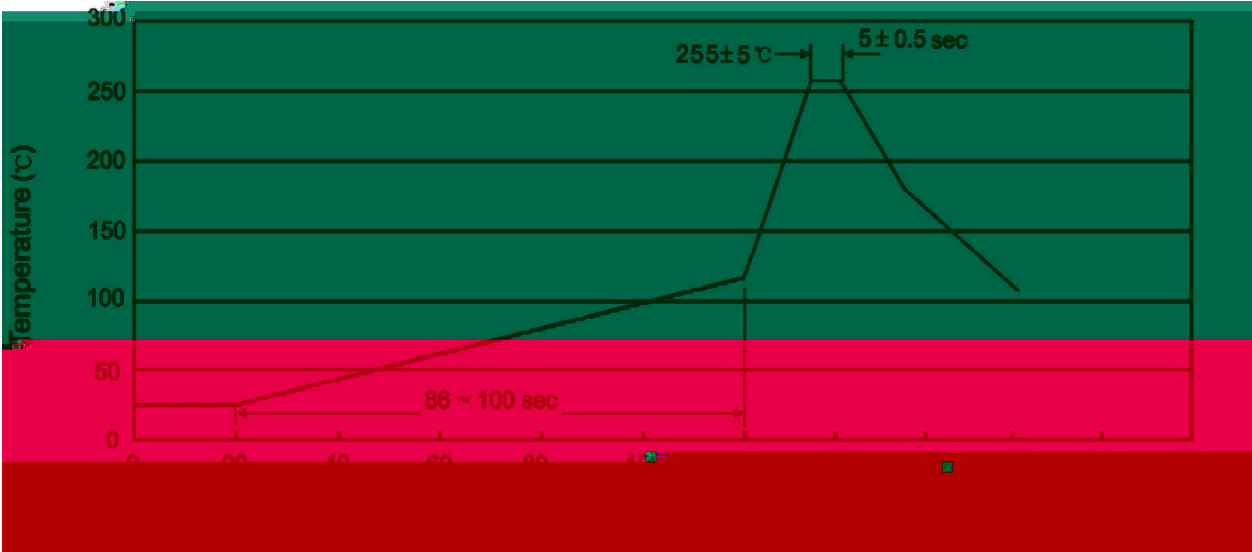
MUR2060

Product Type.

****:

Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- 1

25 150

60 90sec;
- 2

255 5

5 0.5sec;
- 3

2 10

/sec.
- 1.Preheating:25~150

, Time:60~90sec.
- 2.Peak Temp.:255 5

, Duration:5 0.5sec.
3. Cooling Speed: 2~10

/sec.

/ Resistance to Soldering Heat Test Conditions

270 5 10 1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type 封装形式	Units 包装数量		Dimension 包装尺寸 (unit: mm ³)
	Units/Bag 只/袋	Units/Inner Box 只/盒	